

GENERAL DESCRIPTION

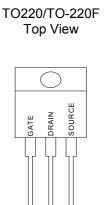
虹冠電

This high voltage MOSFET uses an advanced termination \blacklozenge scheme to provide enhanced voltage-blocking capability without degrading performance over time. In addition, this advanced MOSFET is designed to withstand high energy in avalanche and commutation modes. The new energy \blacklozenge efficient design also offers a drain-to-source diode with a fast recovery time. Designed for high voltage, high speed switching applications in power supplies, converters and PWM motor controls, these devices are particularly well suited for bridge circuits where diode speed and commutating safe operating areas are critical and offer additional and safety margin against unexpected voltage transients.

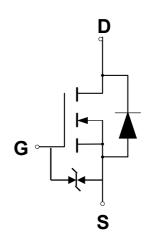
PIN CONFIGURATION

FEATURES

- Robust High Voltage Termination
- Avalanche Energy Specified
- Source-to-Drain Diode Recovery Time Comparable to a **Discrete Fast Recovery Diode**
- Diode is Characterized for Use in Bridge Circuits
- I_{DSS} and V_{DS}(on) Specified at Elevated Temperature
- **Ciss** improvement



SYMBOL



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS

| Rating | | Value | Unit |
|--|-----------------------------------|------------|--------------|
| Drain to Current – Continuous | | 13 | А |
| - Pulsed | I _{DM} | 39 | |
| Gate-to-Source Voltage – Continue | V _{GS} | ±30 | V |
| Total Power Dissipation – TO220 | | 193 | W |
| – TO220FP | | 47 | |
| Derate above 25°C – TO220 | | 1.54 | W /°C |
| – TO220FP | | 0.38 | |
| Operating and Storage Temperature Range | T _J , T _{STG} | -55 to 150 | °C |
| Single Pulse Drain-to-Source Avalanche Energy $-$ T _J = 25 $^{\circ}$ C | | 605 | mJ |
| $(V_{DD} = 100V, V_{GS} = 10V, I_L = 11A, L = 10mH, R_G = 25\Omega)$ | | | |
| Thermal Resistance – Junction to Case -TO220 | θ _{JC} | 0.64 | °C/W |
| Junction to Case -TO220FP | | 3.7 | |
| Junction to Ambient -TO220, TO220FP | θ_{JA} | 62.5 | |
| Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds | | 260 | °C |
| ESD SENSITIVITY – HBM, C=100pF, R=1.5kΩ | | 2000 | V |



ORDERING INFORMATION

| Part Number | Package |
|-------------------|---------|
| GPT13N50GN220* | TO-220 |
| GPT13N50DGN220FP* | TO-220F |

*Note: G : Suffix for PB Free Product

ELECTRICAL CHARACTERISTICS

Unless otherwise specified, $T_J = 25^{\circ}C$.

| | | | GPT13N50 | | | |
|--|--|----------------------|----------|------|------|-------|
| Characteristic | | Symbol | Min | Тур | Max | Units |
| Drain-Source Breakdown Voltage | | V _{(BR)DSS} | 500 | | | V |
| $(V_{GS} = 0 V, I_D = 250 \mu A)$ | | | | | | |
| Drain-Source Leakage Current | | I _{DSS} | | | 1 | μA |
| $(V_{DS} = 500 \text{ V}, V_{GS} = 0 \text{ V})$ | | | | | | |
| Gate-Source Leakage Current-Forward | | I _{GSSF} | | | 100 | nA |
| $(V_{gsf} = 30 \text{ V}, V_{DS} = 0 \text{ V})$ | | | | | | |
| Gate-Source Leakage Current-Reverse | | I _{GSSR} | | | 100 | nA |
| $(V_{gsr} = -30 \text{ V}, V_{DS} = 0 \text{ V})$ | ′ _{gsr} = -30 V, V _{DS} = 0 V) | | | | | |
| Gate Threshold Voltage | | V _{GS(th)} | 3 | | 5 | V |
| $(V_{DS} = V_{GS}, I_D = 250 \ \mu A)$ | | | | | | |
| Static Drain-Source On-Resistance (V_{GS} = 10 V, I_D = 6.5A) * | | R _{DS(on)} | | | 0.49 | Ω |
| Forward Transconductance (V_{DS} = 15 V, I_D = 6.5A) * | | g fs | | 8.7 | | S |
| Input Capacitance | (V _{DS} = 25 V, V _{GS} = 0 V, | Ciss | | 1578 | | pF |
| Output Capacitance | f = 1.0 MHz | Coss | | 180 | | pF |
| Reverse Transfer Capacitance | i – i.u winz) | C _{rss} | | 9.8 | | pF |
| Turn-On Delay Time | | t _{d(on)} | | 33 | | ns |
| Rise Time | $(V_{DD} = 250 \text{ V}, I_D = 13 \text{ A},$ | tr | | 59 | | ns |
| Turn-Off Delay Time | R _G = 25Ω) * | t _{d(off)} | | 75 | | ns |
| Fall Time | | t _f | | 34.8 | | ns |
| Total Gate Charge | $()/_{} = 400)/_{} = 130$ | Qg | | 31 | | nC |
| Gate-Source Charge | (V _{DS} = 400 V, I _D = 13 A, V _{GS} = 10 V)* | Q_gs | | 8.7 | | nC |
| Gate-Drain Charge | VGS - 10 V) | Q_gd | | 12 | | nC |
| SOURCE-DRAIN DIODE CHARA | ACTERISTICS | | | | | |
| Forward On-Voltage(1) | (Is =13 A, V _{GS} = 0 V, | V _{SD} | | | 1.5 | V |
| Forward Turn-On Time | $(I_{S} = I_{3} A, V_{GS} = 0 V,$ $d_{IS}/d_{t} = 100A/\mu s)$ | t _{on} | | ** | | ns |
| Reverse Recovery Time | $u_{\rm IS}/u_{\rm t} = 100 A/\mu S$ | t _{rr} | | 450 | | ns |

* Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%

** Negligible, Dominated by circuit inductance



GPT13N50 / GPT13N50D

POWER FIELD EFFECT TRANSISTOR

TYPICAL ELECTRICAL CHARACTERISTICS

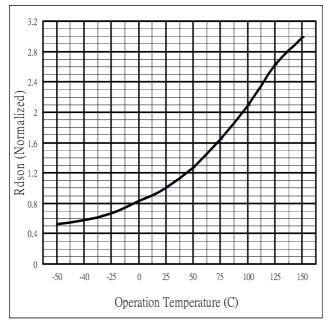


Fig 1. On-Resistance Variation with vs. Temperature

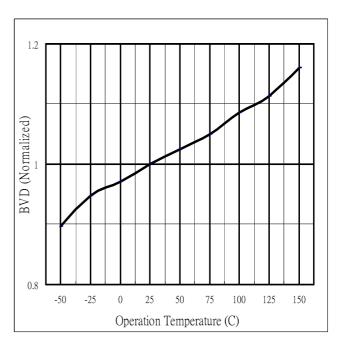


Fig.2 Breakdown Voltage Variation vs. Temperature

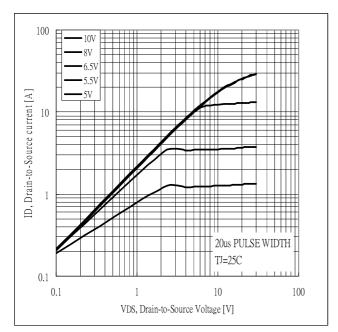


Fig 3. Typical Output Characteristics

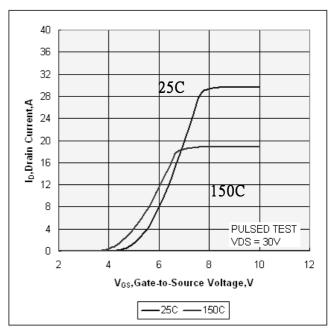


Fig 5. Typical Transfer Characteristics



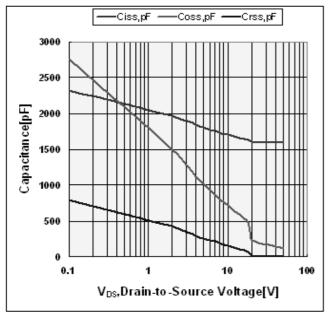


Fig 6. Typical Capacitance Vs. Gate-to-Source Voltage



POWER FIELD EFFECT TRANSISTOR

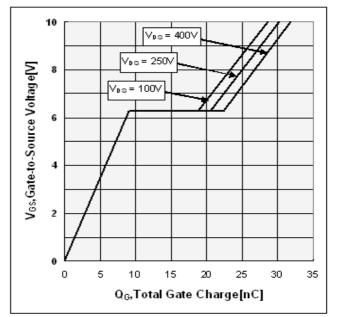


Fig 6. Typical Gate Charge Vs. Drain-to-Source Voltage



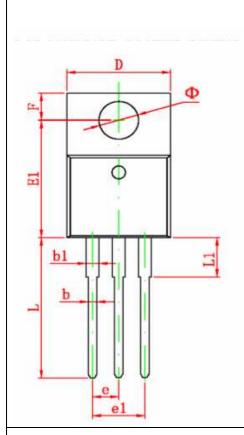


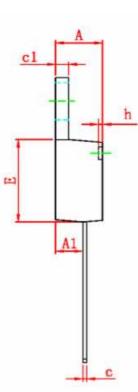
GPT13N50 / GPT13N50D

POWER FIELD EFFECT TRANSISTOR

PACKAGE DIMENSION

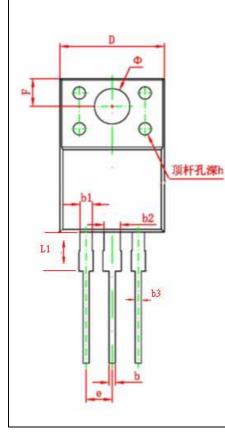


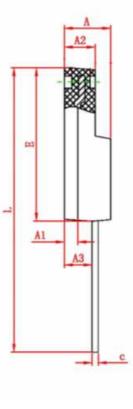




| Course 1 and | Dimensions In Millimete | | |
|--------------|-------------------------|-------|--|
| Symbol | Min. | Мах | |
| А | 4.40 | 4.80 | |
| A1 | 2.10 | 2.84 | |
| b | 0.71 | 0.91 | |
| b1 | 1.17 | 1.37 | |
| С | 0.30 | 0.60 | |
| c1 | 1.17 | 1.47 | |
| D | 9.40 | 10.60 | |
| E | 8.40 | 9.60 | |
| е | 2.54 TYP. | | |
| el | 4.90 | 5.60 | |
| F | 3.00 REF. | | |
| Φ | 3.50 REF. | | |
| h | 0.00 | 0.30 | |
| L | 12.50 | 14.00 | |
| L1 | 3.50 | 4.00 | |

TO-220F





| C h l | Dimensions | In Millimete | |
|--------|------------|--------------|--|
| Symbol | Min. | Max | |
| А | 3.80 | 4.70 | |
| A1 | 1.3 REF. | | |
| A2 | 2.20 | 3.20 | |
| A3 | 2.10 | 3.20 | |
| b | 0.30 | 0.95 | |
| b1 | 1.00 | 1.75 | |
| b2 | 1.00 | 1.75 | |
| b3 | 0.50 | 0.80 | |
| С | 0.30 | 0.90 | |
| D | 9.90 | 10.40 | |
| E | 14.60 | 16.20 | |
| е | 2.54 TYP. | | |
| F | 3.00 REF. | | |
| Φ | 3.50 REF. | | |
| h | 0.00 | 0.30 | |
| L | 28.00 | 30.00 | |
| L1 | 3.20 | 3.55 | |



IMPORTANT NOTICE

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